Cell K Y Wong

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/12151536/publications.pdf

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11	175	1684188 5	2053705 5
papers	citations	h-index	g-index

11	11	11	221
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Molecular modeling of temperature dependence of solubility parameters for amorphous polymers. Journal of Molecular Modeling, 2012, 18, 2333-2341.	1.8	67
2	Functionalization-induced changes in the structural and physical properties of amorphous polyaniline: a first-principles and molecular dynamics study. Scientific Reports, 2016, 6, 20621.	3.3	40
3	Interfacial Adhesion Study for SAM Induced Covalent Bonded Copper-EMC Interface by Molecular Dynamics Simulation. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 297-308.	1.3	24
4	Thiol-based self-assembly nanostructures in promoting interfacial adhesion for copper-epoxy joint. Applied Physics Letters, 2009, 94, .	3.3	19
5	Thiol based chemical treatment as adhesion promoter for Cu-epoxy interface. , 2008, , .		6
6	A multiscale method to predict delamination in Cu-epoxy systems in electronic packages. , 2009, , .		6
7	Synergistic Toughening of Epoxyâ€"Copper Interface Using a Thiol-Based Coupling Layer. Journal of Adhesion Science and Technology, 2011, 25, 2081-2099.	2.6	5
8	Hydrophobic self assembly molecular layer for reliable Cu-epoxy interface. , 2009, , .		4
9	Hydrophobic self-assembly monolayer structure for reduction of interfacial moisture diffusion. , 2009, , .		4
10	Kinetics Study of Disulfide Self Assembly Monolayer (SAM) Deposition for Cu-EMC Adhesion Promotion. , 2006, , .		0
11	Kinetic Study of Disulfide Molecular Film Deposition for Cu-EMC Adhesion Promotion. Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International, 2006, , .	0.0	0